

### **AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1-2. (Canceled)

3-6. (Withdrawn)

7-18. (Canceled)

19. (New) A method for packing a plurality of Micro Electro Mechanical System (MEMS) devices formed on a semiconductor substrate, the method comprising the steps of:

covering a plastic film over the semiconductor substrate;

pressing the plastic film onto the semiconductor substrate; and

bonding the plastic film and the semiconductor substrate around a perimeter of each of the plurality of MEMS devices formed on the semiconductor substrate, by radiating light through the plastic film and into the semiconductor substrate;

wherein the light has a wavelength that is absorbed into the semiconductor substrate but not into the plastic film.

20. (New) The method set forth in claim 19, further comprising the step of adjusting the temperature of the semiconductor substrate to a predetermined degree.

21. (New) The method set forth in claim 19, wherein the plastic film has an alignment mark to be aligned with the semiconductor substrate.
22. (New) The method set forth in claim 19, wherein the plastic film has a plurality of recesses corresponding to the plurality of MEMS devices.
23. (New) The method set forth in claim 19, wherein light shielding materials are applied to predetermined parts of the plastic film.
24. (New) The method set forth in claim 19, wherein the plastic film is a thermoplastic film.
25. (New) The method set forth in claim 19, wherein an adhesive is applied to a bonding part of the plastic film so as to bond to the semiconductor substrate around perimeters of the plurality of MEMS devices.
26. (New) A plastic film for packing a plurality of Micro Electro Mechanical System (MEMS) devices formed on a semiconductor substrate, the plastic film covering over a surface of the semiconductor substrate and having a plurality of recesses corresponding to the plurality of MEMS devices.
27. (New) An apparatus for packing a plurality of Micro Electro Mechanical Systems (MEMS) devices formed on a semiconductor substrate, the apparatus comprising:
- a pressure means to press a plastic film covering over the semiconductor substrate;

a bonding means to bond the plastic film and the semiconductor substrate around a perimeter of each of the plurality of MEMS devices formed on the semiconductor, by radiating light through the pressure means and plastic film, and into the semiconductor substrate;

wherein the light has a wavelength that is absorbed into the semiconductor substrate but not into the pressure means and the plastic film.

28. (New) The apparatus set forth in claim 27, further comprising a temperature adjusting means to adjust the temperature of the semiconductor substrate to a predetermined degree.